

PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1
 Stylesheet Version v1.2

EPAS ID: PAT6902468

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
TETSUAKI INADA	08/19/2021
TAKESHI YASUI	08/18/2021
RECEIVING PARTY DATA	
Name:	KOKUSAI ELECTRIC CORPORATION
Street Address:	3-4, KANDAKAJI-CHO, CHIYODA-KU
City:	TOKYO
State/Country:	JAPAN
Postal Code:	101-0045
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	29806527
CORRESPONDENCE DATA	
Fax Number:	
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
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Correspondent Name:	FITCH, EVEN, TABIN & FLANNERY
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Address Line 2:	SUITE 2100
Address Line 4:	CHICAGO, ILLINOIS 60603
ATTORNEY DOCKET NUMBER:	20372-153329-US
NAME OF SUBMITTER:	ALAN E. SCHIAVELLI
SIGNATURE:	/Alan E. Schiavelli/
DATE SIGNED:	09/07/2021
Total Attachments: 2	
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ASSIGNMENT

(譲 渡 証)

As a below named inventor, I hereby declare that:

IN CONSIDERATION of the sum of One Dollar (\$1.00) or the equivalent thereof, and other good and valuable consideration paid to me citizen of Japan by KOKUSAI ELECTRIC CORPORATION a corporation organized under the laws of Japan, located at 3-4, Kandakaji-cho, Chiyoda-ku, Tokyo, Japan receipt of which is hereby acknowledged I do hereby sell and assign to said KOKUSAI ELECTRIC CORPORATION its successor and assigns, all my right, title and interest, in and for the United States of America, in and to

SUBSTRATE MOUNTING PLATE FOR SUBSTRATE PROCESSING APPARATUS

invented by me (if only one is named below) or us (if plural inventors are named below) and described in the application for United States Letters Patent therefor, executed on even date herewith, and all United States Letters Patent which may be granted therefor, and all divisions, continuations and extensions thereof, the said interest being the entire ownership of the said Letters Patent when granted, to be held and enjoyed by said KOKUSAI ELECTRIC CORPORATION its successor, assigns or other legal representatives, to the full end of term for which said Letters Patent may be granted as fully and entirely as the same would have been held and enjoyed by me or us if this assignment and sale had not been made;

And I hereby agree to sign and execute any further documents or instruments which may be necessary, lawful, and proper in the prosecution of the above-named application or in the preparation and prosecution of any continuing, continuation-in-part, substitute, divisional, renewal, reviewed or reissue applications or in any amendment, extension, or interference proceedings, or otherwise to secure the title thereto in said assignee;

And I do hereby authorize and request the Commissioner of Patents to issue said Letters Patent to said KOKUSAI ELECTRIC CORPORATION

Signed on the date(s) indicated aside our signatures:

INVENTOR(S)
(発明者フルネームサイン)

Date Signed
(署名日)

1)	_____ Tetsuaki INADA _____	_____
2)	_____/Takeshi Yasui/_____ Takeshi YASUI _____	Aug 18,2021 _____
3)	_____	_____
4)	_____	_____
5)	_____	_____
6)	_____	_____
7)	_____	_____
8)	_____	_____
9)	_____	_____
10)	_____	_____

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INVENTOR(S)
(発明者フルネームサイン)

Date Signed
(署名日)

1) /Tetsuaki Inada/	Tetsuaki INADA	Aug 19,2021
2) _____	Takeshi YASUI	_____
3) _____		_____
4) _____		_____
5) _____		_____
6) _____		_____
7) _____		_____
8) _____		_____
9) _____		_____
10) _____		_____